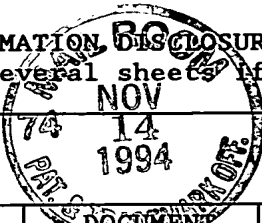


FORM PTO-1449
(REV. 7-80)U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
26860/0033;37 USASERIAL NO.
08/276,797INFORMATION DISCLOSURE CITATION
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Mark D. OwenFILING DATE
July 18, 1994GROUP
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U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
Am	AA	5 1 5 3 4 0 8	10/06/92	Handford et al.	219	121.64	
Am	AB	4 9 1 5 9 8 1	04/10/90	Traskos et al.	427	53.1	
Am	AC	4 8 3 2 7 8 8	05/23/89	Nemiroff	156	643	
	AD						
	AE						
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	AK						

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FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
	AL						
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OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

Am	AN	Pete Singer, "The Interconnect Challenge: Filling Small, High Aspects Ratio Contact Holes," <i>Semiconductor International</i> , August 1994, pp. 57-64					
Am	AO	"Printed Circuit Operations - A View from Inside," Unisys					
Am	AP	Richard Harris et al., "MCM Micromachining: Nd:YAG UV Laser Process is a New Option," <i>Electro Scientific Industries, Inc.</i> , Spring 1993					
Am	AQ	"LaserPulse," <i>Electro Scientific Industries, Inc.</i> , Fall 1993, pp. 1-7					
Am	AR	Y.S. Liu, "Laser Metal Deposition for High-Density Interconnect," <i>Optics & Photonics News</i> , June 1992, pp. 10-14					
Am	AS	Friedrich G. Bachmann, "Large scale industrial application for excimer-lasers; via-hole-drilling by photo-ablation," <i>SPIE</i> , Vol. 1361, Physical Concepts of Materials for Novel Optoelectronic Device Applications, 1990, pp. 500-511					

EXAMINER

Gregory Mills

DATE CONSIDERED

10-6-95

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